

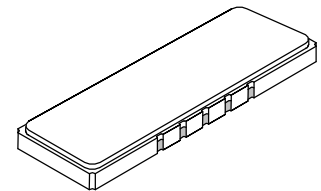


- **Designed for GSM BTS Receiver IF Applications**
- **Low Insertion Loss**
- **Excellent Size-to-Performance Ratio**
- **Hermetic SMP-75 Surface-Mount Case**
- **Unbalanced Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)**



SF1088A

170.6 MHz SAW Filter



SMP-75

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_C	1	170.600			MHz
Passband	IL	1, 2			8.0	dB
Insertion Loss at f_C						
1 dB Passband			±90			kHz
Amplitude Ripple over f_C ±90 kHz					1.0	dB _{p-p}
Group Delay Variation over f_C ±190 kHz	GDV	1, 2, 3		<500	1000	ns _{p-p}
Rejection			13	15		dB
fc-0.6 to fc-0.4 and fc+0.4 to fc+0.6 MHz			27	35		
fc-0.8 to fc-0.6 and fc+0.6 to fc+0.8 MHz			40	45		
fc-1.6 to fc-0.8 and fc+0.8 to fc+1.6 MHz			43	55		
fc-3.0 to fc-1.6 and fc+1.6 to fc+3.0 MHz			47	55		
fc-5.8 to fc-3.0 and fc+3.0 to fc+5.8 MHz			50	55		
fc-35 to fc-5.8 and fc+5.8 to fc+35 MHz			45	55		
fc-75 to fc-35 and fc+35 to 75 MHz			40			
DC to fc-75 and fc+75 to fc+1000 MHz						
Operating Temperature Range	T_A	1	-10		+85	°C

Impedance Matching to 50 Ω unbalanced	External L-C
Case Style	SMP-75 19 x 6.5 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week)	RFM SF1088A YYWW

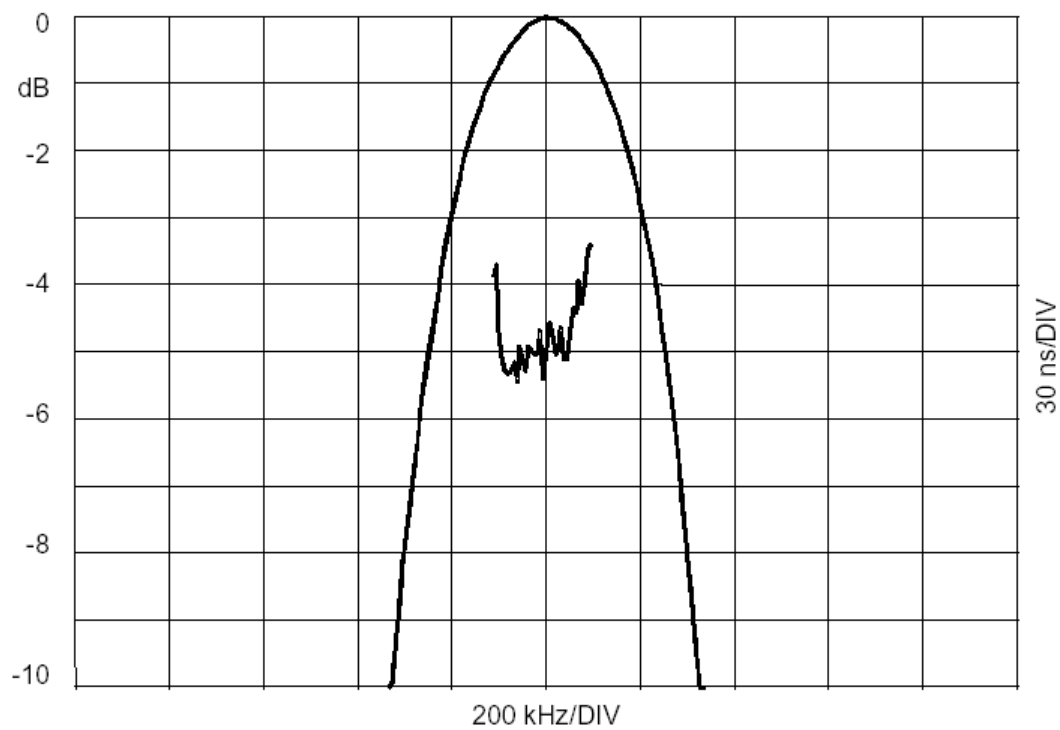
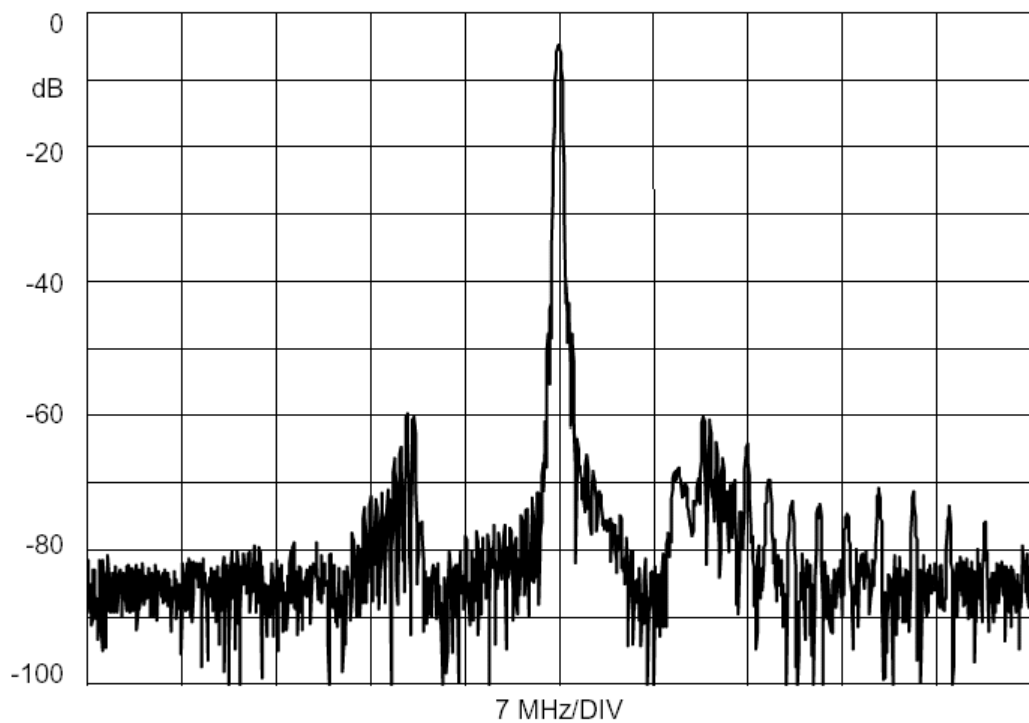
Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_C .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. Electrostatic Sensitive Device. Observe precautions for handling.



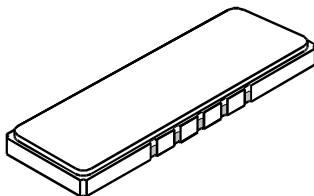
Electrical Connections

Connection	Terminals
Port 1 Hot	10
Port 1 Gnd Return	1
Port 2 Hot	5
Port 2 Gnd Return	6
Case Ground	All others



SMP-75 Case

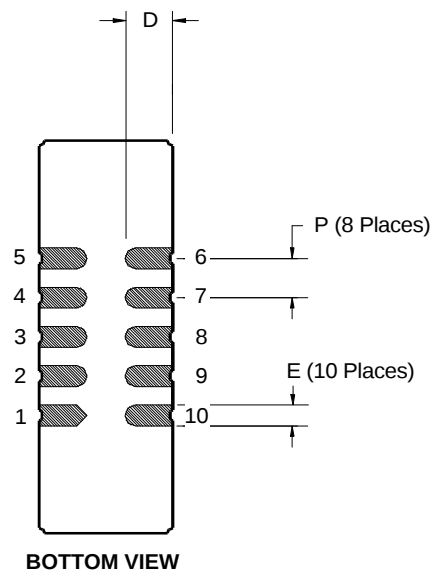
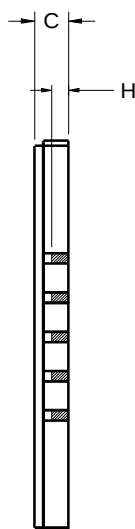
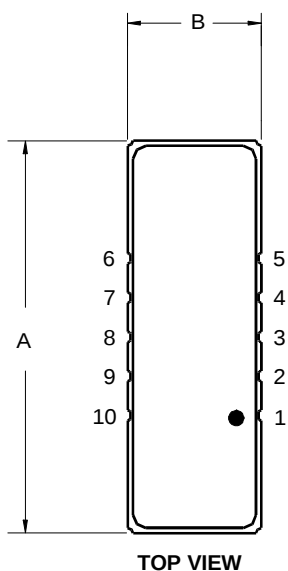
10-Terminal Ceramic Surface-Mount Case
19 x 6.5 mm Nominal Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	18.80	19.00	19.30	0.740	0.748	0.760
B	6.30	6.50	6.80	0.248	0.256	0.268
C		1.75	2.00		0.069	0.079
D		2.29			0.090	
E		1.02			0.040	
H		1.0			0.039	
P		1.905			0.075	

Materials	
Solder Pad Termination	Au plating 30 - 60 μ inches (76.2-152 μ m) over 80-200 μ inches (203-508 μ m) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μ inches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

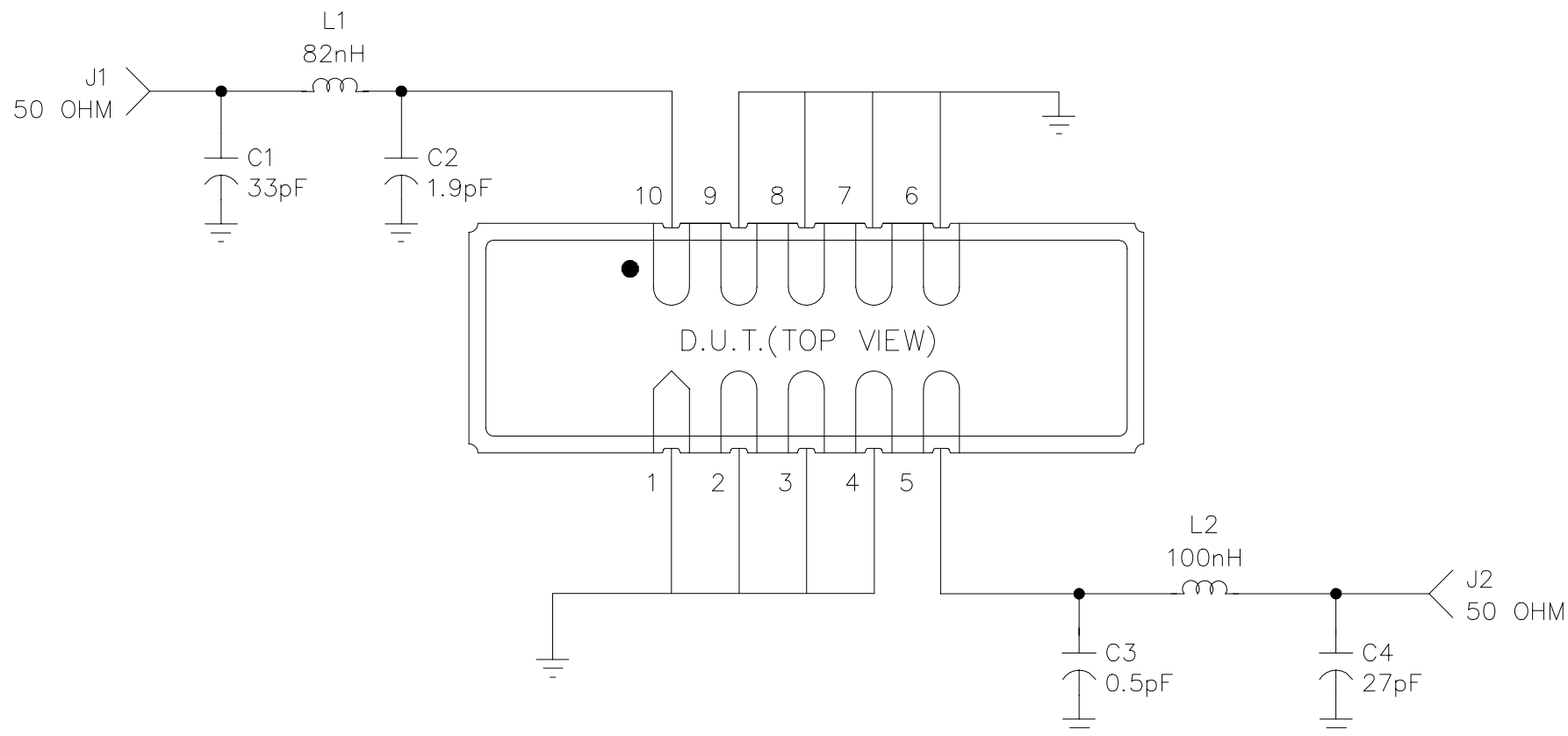
Electrical Connections		
Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot



NOTES:

1. NOTE PROPER ORIENTATION OF INDUCTORS L1 & L2. THEY ARE TO BE POSITIONED 90° TO EACH OTHER.
2. SOLDER SURFACE MOUNT PACKAGE TO TEST SIDE OF PCB. SOLDER 10 PLACES AS SHOWN.
3. PACKAGE PIN 10 INDICATOR

REV	ECN NO.	DESCRIPTION	DATE
A	6724	INITIAL RELEASE	5/28/98
B	7000	ROTATE VIEW 180	3SEP98



DRAWN BY/DATE: J. LAYTON 05/28/98

TITLE: ASSEMBLY DIAGRAM, SF1088A(DEMO)

RF Monolithics, Inc.
DALLAS, TEXAS 75244

CHECKED/APPROVED

SIZE
A

CODE IDENT
2U874

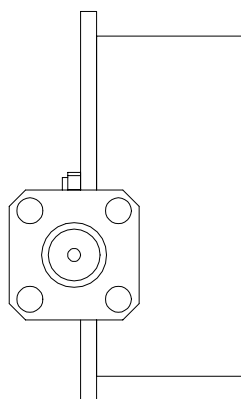
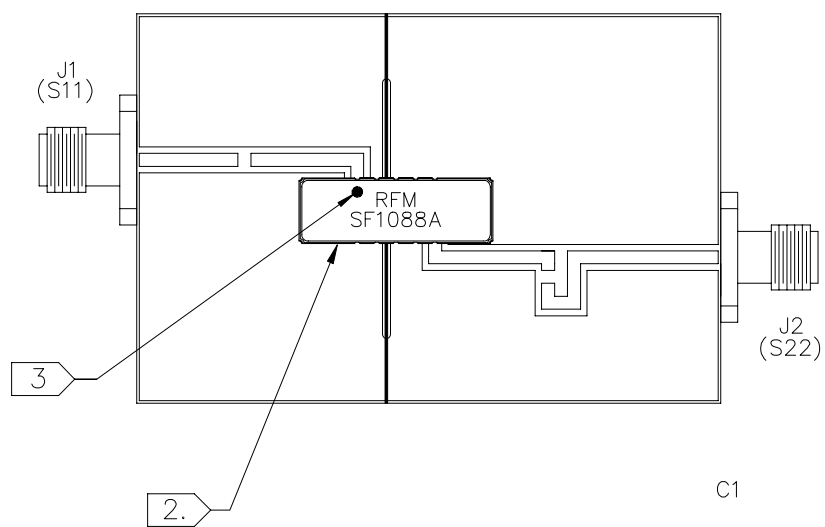
DWG.
NO.

SF1088A-000

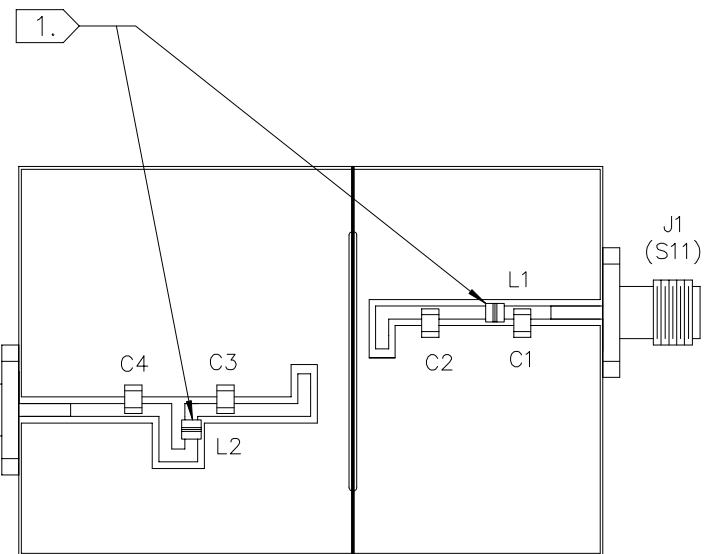
REV
B

SHEET
1/3

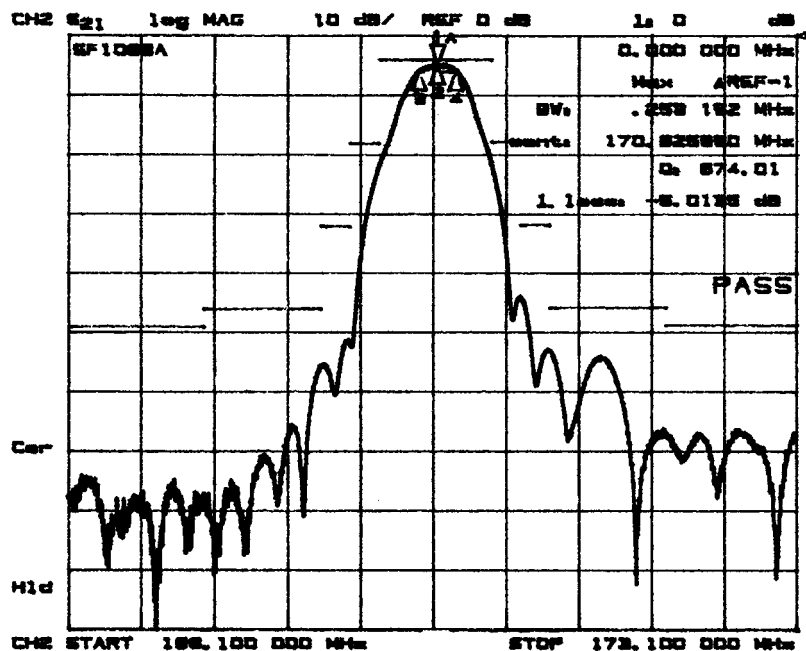
TEST SIDE



SHLD1



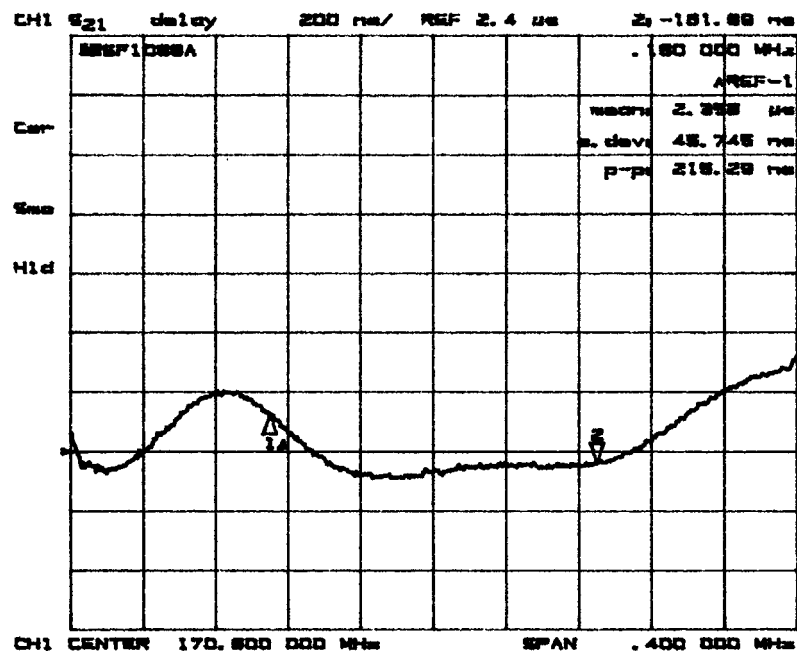
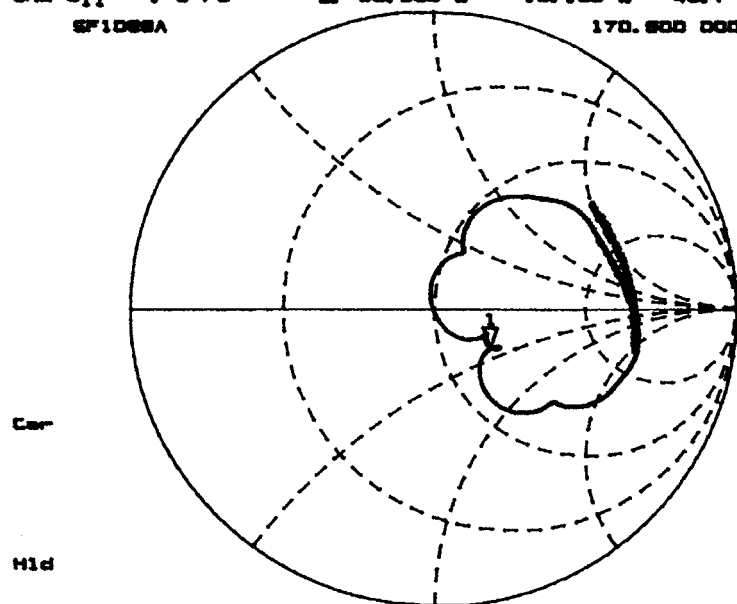
COMPONENT SIDE



CH2 S₁₁ 1 U FS 1.0 58.888 a -18.188 a 48.7 pF

SF1088A

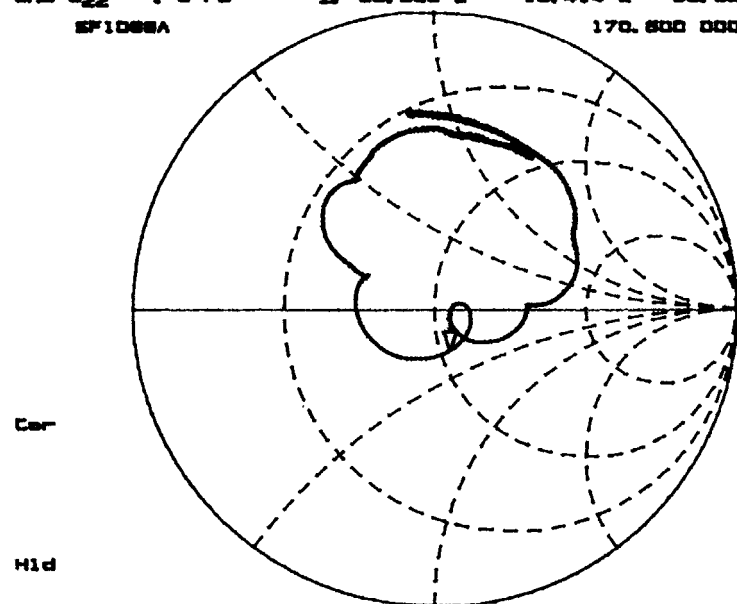
170.800 000 MHz



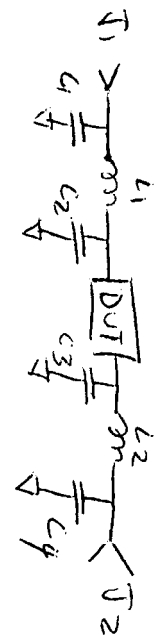
CH2 S₂₂ 1 U FS 1.0 58.288 a -18.414 a 80.824 pF

SF1088A

170.800 000 MHz



SF1088A
(DEMO)
4-28-98



$L_1 = 82 \text{ nH}$
 $L_2 = 100 \text{ nH}$
 $C_1 = 33 \text{ pF}$
 $C_2 = 1.9 \text{ pF}$
 $C_3 = 0.5 \text{ pF}$
 $C_4 = 27 \text{ pF}$

REV: ~~WBS~~ 3/3

BILL OF MATERIALS

<u>PART IDENTIFIER</u>	<u>DESCRIPTION 1</u>	<u>DESCRIPTION 2</u>	<u>QTY/ASSY</u>	<u>REFERENCE DESCRIPTION</u>
SF1088A-DEMO	DEMO BOARD,SF1088A			
400-1387-001	PCB,DEMO BOARD,19MM		1.0000	
400-0533-001	SHIELD,TO-39 TEST FIXTURE		1.0000	
SF1088A-000	ASSY DIAGRAM,DEMO BOARD,	SF1088A	0	
SF1088A-LRIP	FILTER,SM,170.600MHZ		1.0000	
500-0003-330	CAP,CHIP,NPO,33(J),STD		1.0000	C 1
500-0003-019	CAP,CHIP,NPO,1.9(C),STD		1.0000	C 2
500-0003-005	CAP,CHIP,NPO,0.5(C),STD		1.0000	C 3
500-0003-270	CAP,CHIP,NPO,27(J),STD		1.0000	C 4
500-0248-001	CONN,COAX,FLANGE MT.JACK	4 HOLE	2.0000	J 1,2
500-0781-820	IND,CHIP,0805CS,82NH,2%		1.0000	L 1
500-0781-101	IND,CHIP,0805CS,100NH,2%		1.0000	L 2



SIZE

A

FSCM NO.

2U874

DWG NO.

SF1088A-DEMO

SCALE

NONE

W/O or ECN

6724

REV

A

SHEET

1

OF **2**

REV HISTORY			
REV	ECN	DATE	DESCRIPTION
A	6724	06/01/98	INITIAL RELEASE

		SIZE A	FSCM NO. 2U874	DWG NO. SF1088A-DEMO	
	SCALE NONE	W/O or ECN 6724		REV A	SHEET 2 OF 2